



LCA715 Single-Pole, Normally Open 6-Pin OptoMOS[®] Relay

Parameter	Ratings	Units
Blocking Voltage	60	V _P
Load Current	2.2	A _{rms} / A _{DC}
On-Resistance (max)	0.15	Ω

Features

- 3750V_{rms} Input/Output Isolation
- Low Drive Power Requirements
- High Reliability
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Small 6-Pin Package
- Flammability Rating UL 94 V-0
- Surface Mount and Tape & Reel Versions Available

Applications

- Instrumentation
- Multiplexers
- Data Acquisition
- · Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

The LCA715 is a 60V single-pole, normally open (1-Form-A) Solid State Relay. It uses optically coupled MOSFET technology to provide $3750V_{rms}$ of input to output isolation, and features an ultra-low on-resistance for high-current operation.

Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient infrared LED.

Offering the superior reliability associated with semiconductor devices, the LCA715 can be used to replace mechanical relays. Because it has no moving parts, it can offer faster, bounce-free switching in a more compact surface mount or thru-hole package.

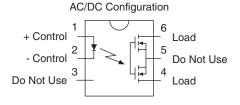
Approvals

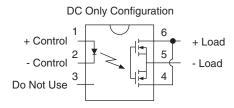
- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1172007
- EN/IEC 60950-1 Certified Component: Certificate available on our website

Ordering Information

Part #	Description
LCA715	6 Pin DIP (50/Tube)
LCA715S	6 Pin Surface Mount (50/Tube)
LCA715STR	6 Pin Surface Mount (1000/Reel)

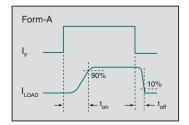
Pin Configuration







Switching Characteristics of Normally Open Devices





Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of

the manufacturing testing requirements.

data sheet is not implied.

Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	60	V _P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	А
Input Power Dissipation	70	mW
Total Power Dissipation ¹	800	mW
ESD, Human Body Model	8	kV
Isolation Voltage, Input to Output	3750	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 6.67 mW / °C

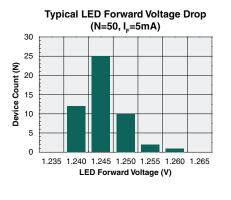
Electrical Characteristcs @ 25°C

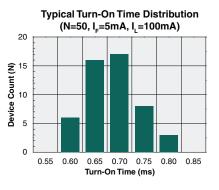
Parameter Conditions Symbol Min Max Units Тур **Output Characteristics** Load Current Continuous, AC/DC Configuration 2.2 . _ A_{rms} / A_{DC} Continuous, Free Air I_{L} Continuous, DC Configuration 4 --A_{DC} t<10ms ±10 Peak I_{LPK} -- A_p On-Resistance 1 AC/DC Configuration 0.12 0.15 $I_F=5mA$, $I_L=1A$ R_{ON} Ω 0.038 0.05 DC Configuration -Off-State Leakage Current ILEAK $I_{r}=0mA, V_{I}=60V_{P}$ --1 μA Switching Speeds Turn-On 0.7 2.5 ms t_{on} I_F =5mA, V_L =10V Turn-Off 0.115 0.25 ms t_{off} I_⊏=0mA, f=1MHz **Output Capacitance** $V_1 = 10V$ 200 -110 C_{OUT} pF $V_1 = 50V$ 60 -_ **Input Characteristics** Input Control Current to Activate 0.9 $I_1 = 1A$ -5 mΑ $|_{F}$ 0.4 Input Control Current to Deactivate mΑ - I_{F} --Input Voltage Drop I_⊏=5mA VF 0.9 1.2 1.5 V **Reverse Input Current** V_R=5V --10 μΑ I_{R} **Common Characteristics** Input to Output Capacitance V_{IO}=0V, f=1MHz CIO -3 pF

¹ Measurement taken within 1 second of on-time.



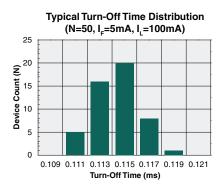




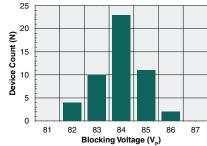


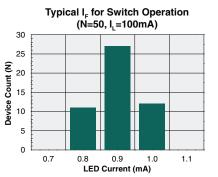
Typical On-Resistance Distribution

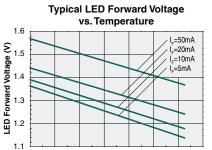
(N=50, I_F=5mA, I_I=1A)

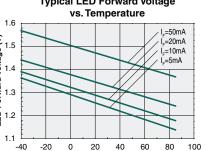


Typical Blocking Voltage Distribution (N=50)





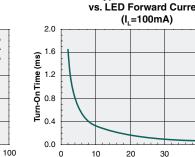




Temperature (°C)

(I_=1A)

20 40



30

25

20

15

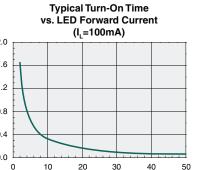
10

5

0

0.110

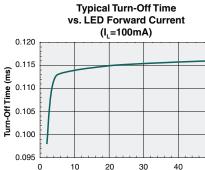
Device Count (N)



LED Forward Current (mA)

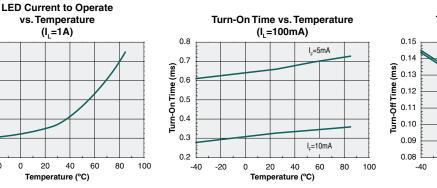
0.111 0.112 0.113 0.114 0.115

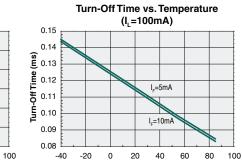
On-Resistance (Ω)



LED Forward Current (mA)

Temperature (°C)





*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C. For guaranteed parameters not indicated in the written specifications, please contact our application department.

1.3

1.2

1.0 0.9

0.8

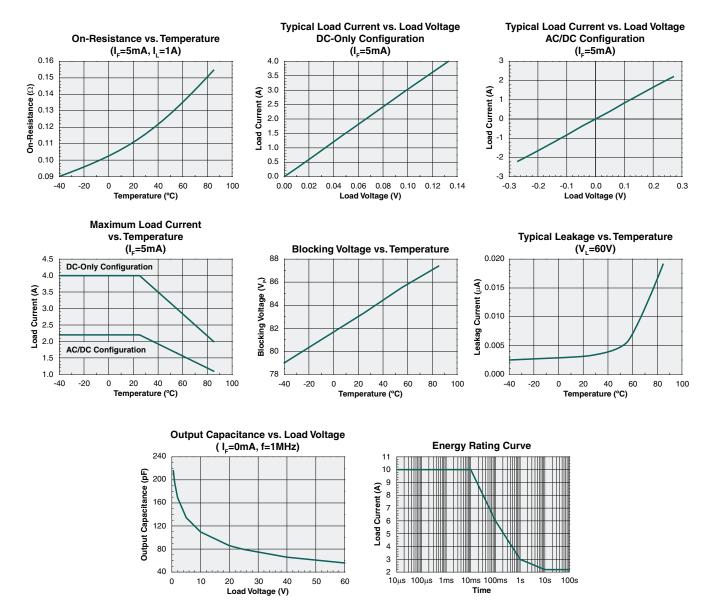
0.7

-40 -20 0

LED Current (mA) 1.1 50



PERFORMANCE DATA*



*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C. For guaranteed parameters not indicated in the written specifications, please contact our application department.



Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification	
LCA715 / LCA715S	MSL 1	

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Soldering Profile

Provided in the table below is the Classification Temperature (T_c) of this product and the maximum dwell time the body temperature of this device may be (T_c - 5)°C or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

Device	Classification Temperature (T _c)	Dwell Time (t _p)	Max Reflow Cycles
LCA715	250°C	30 seconds	1
LCA715S	250°C	30 seconds	3

Board Wash

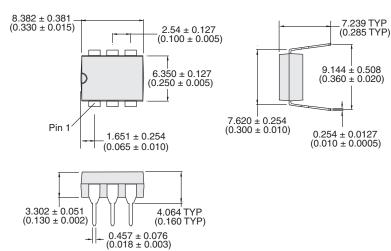
IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.



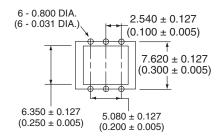


MECHANICAL DIMENSIONS

LCA715

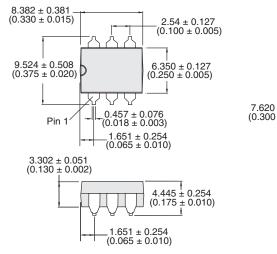


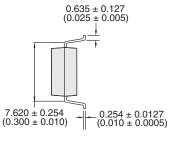
PCB Hole Pattern

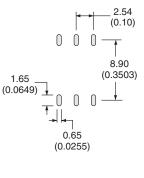


Dimensions mm (inches)

LCA715S





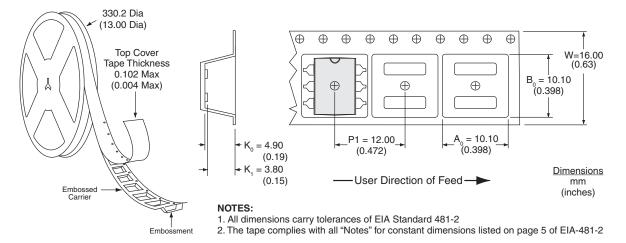


PCB Land Pattern

Dimensions mm (inches)



LCA715STR Tape & Reel



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